



## **SMT power inductors**

Size 6.1 × 5.6 × 4.9 (mm)

**Series/Type:** B82471A1

**Date:** March 2008

SMD

Rated inductance 10  $\mu\text{H}$  to 220  $\mu\text{H}$   
Rated current 0.35 A to 1.44 A



**Construction**

- Ferrite core
- Winding: enamel copper wire
- Winding soldered to terminals
- Plastic terminal carrier

**Features**

- Temperature range up to 150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- Qualification based on AEC-Q200
- RoHS-compatible

**Applications**

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics
- Consumer electronics

**Terminals**

- Base material CuSn6P
- Layer composition Ni-Sn (lead-free)
- Electro-plated

**Marking**

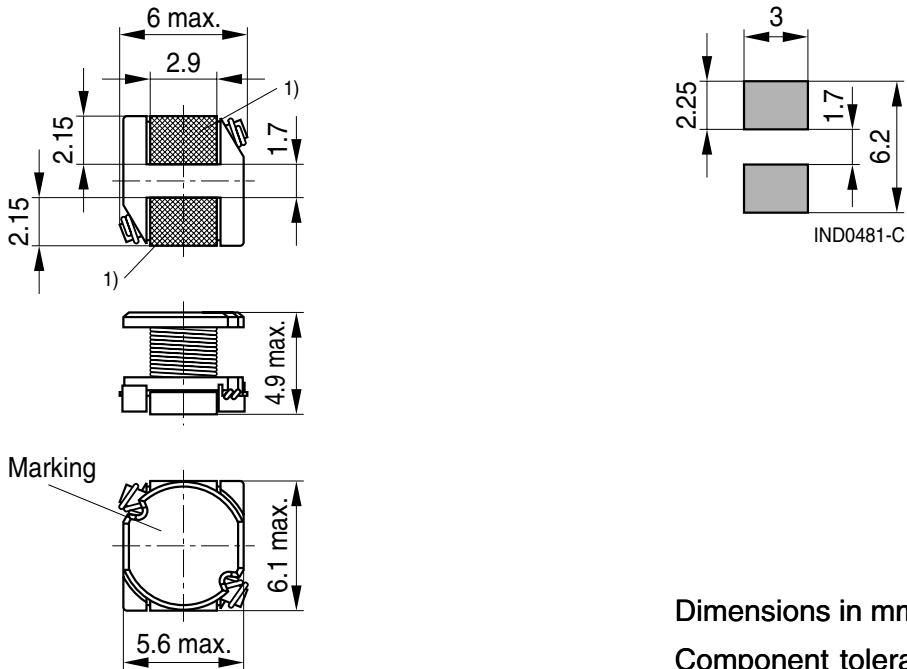
- Marking on component:  
L value ( $\mu\text{H}$ , coded),  
manufacturing date (YWWD)
- Minimum data on reel:  
Manufacturer, ordering code,  
L value, quantity, date of packing

**Delivery mode and packing unit**

- 16-mm blister tape, wound on 330-mm  $\varnothing$  reel
- Packing unit: 1000 pcs./reel

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Dimensional drawing and layout recommendation



Dimensions in mm

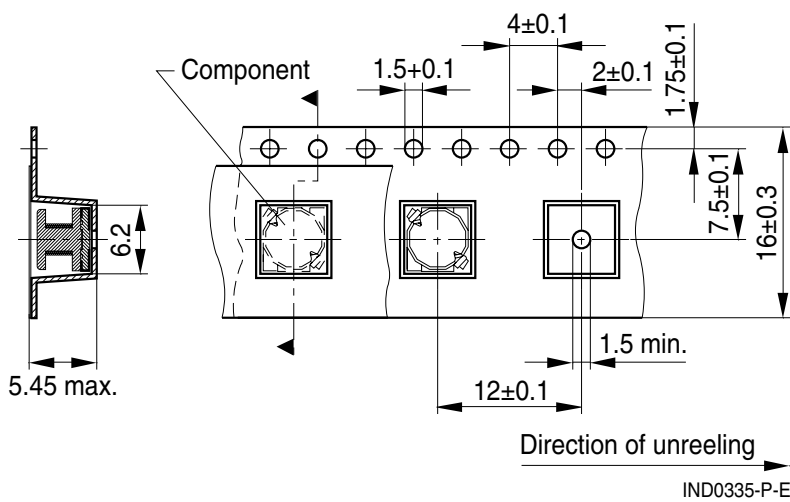
Component tolerances  $\pm 0.2$  mm unless otherwise noted.

1) Soldering area

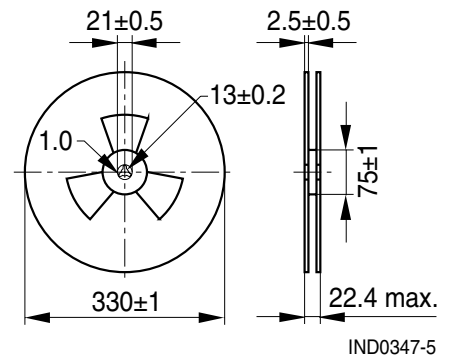
IND0480-Z-E

Taping and packing

Blister tape



Reel



Dimensions in mm

**Technical data and measuring conditions**

Rated inductance $L_R$	Measured with LCR meter Agilent 4284A at frequency $f_L$ , 0.1 V, 20 °C
Rated temperature $T_R$	85 °C
Rated current $I_R$	Max. permissible DC with temperature increase of $\leq 40$ K at rated temperature
Saturation current $I_{sat}$	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance $R_{max}$	Measured at 20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: (245 ±5) °C, (5 ±0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	260 °C, 40 s as referenced in JEDEC J-STD 020C
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 1 g

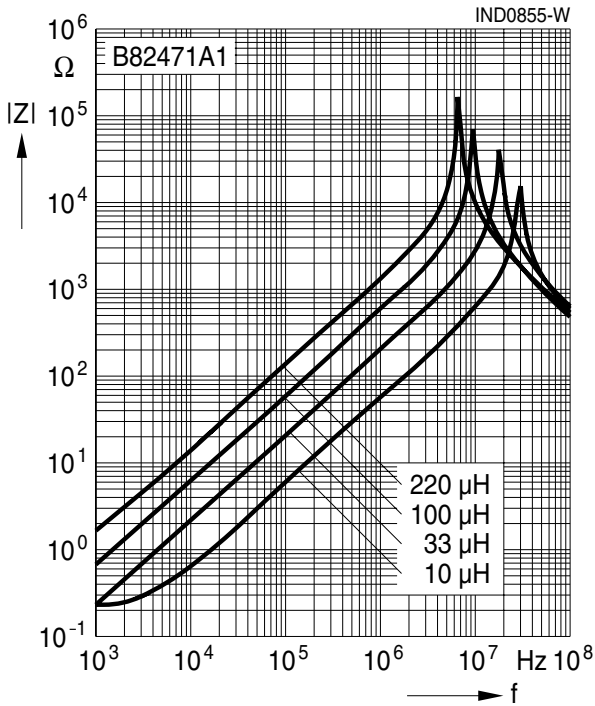
**Characteristics and ordering codes**

$L_R$ $\mu\text{H}$	Tolerance	$f_L$ MHz	$I_R$ A	$I_{sat}$ A	$R_{max}$ $\Omega$	Ordering code
10	$\pm 20\% \triangleq M$	0.1	1.44	1.80	0.10	B82471A1103M000
15		0.1	1.30	1.45	0.14	B82471A1153M000
22		0.1	1.11	1.20	0.18	B82471A1223M000
33		0.1	0.88	1.00	0.23	B82471A1333M000
47		0.1	0.72	0.85	0.37	B82471A1473M000
68	$\pm 10\% \triangleq K$	0.1	0.61	0.70	0.46	B82471A1683K000
100		0.1	0.52	0.60	0.70	B82471A1104K000
150		0.1	0.40	0.48	1.10	B82471A1154K000
220		0.1	0.35	0.38	1.57	B82471A1224K000

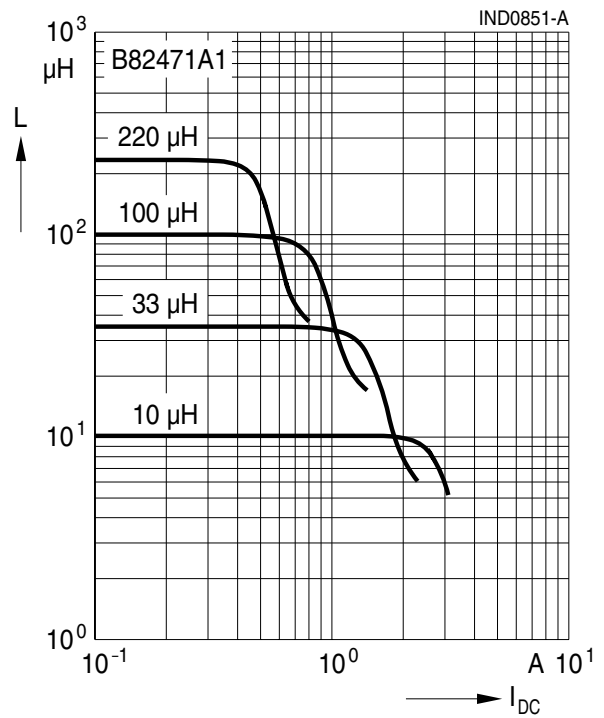
Sample kit available. Ordering code: B8247XX001  
For more information refer to chapter "Sample kits".

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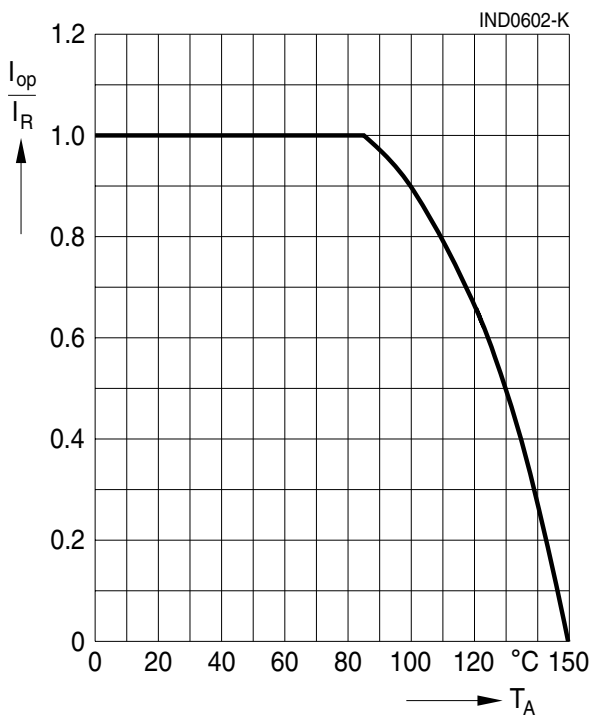
**Impedance |Z| versus frequency f**  
measured with impedance analyzer  
Agilent 4294A, typical values at 20 °C



**Inductance L versus DC load current I<sub>DC</sub>**  
measured with LCR meter Agilent 4284A,  
typical values at 20 °C



**Current derating I<sub>op</sub>/I<sub>R</sub>**  
**versus ambient temperature T<sub>A</sub>**  
(rated temperature T<sub>R</sub> = 85 °C)



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

## Important notes

The following applies to all products named in this publication:

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